Electronic Acknowledgement Receipt FES ID: 1036766 Application Number: 09766477 Confirmation Number: 2137 Title of Invention: Vertical ball grid array integrated circuit package First Named Inventor: Klan Teng Eng Mark E. Courtney Texas Instruments Incorporated P.O. Box 655474, MS 3999 Correspondence Address: Dallas TX 75265 US 9729174418 Filer: Wade J. Brady III/Gracia Sansom Filer Authorized By: Wade J. Brady III Attorney Docket Number: TI-22944.2 Receipt Date: 02-MAY-2006 Filing Date: 19-JAN-2001 Time Stamp: 17:20:03 Application Type: Utility International Application Number: Payment information:

no

Submitted with Payment

File Listing:

Number	Document Description	File Name	File Size(Bytes)	Part	Pages
1		T22944-2-SB96-SB80.pdf	9734	yes	2
	Multipart Description				
	Doc Desc		Start	End	
	Assignee showing of ownership per 37 CFR 3.73(b).		1	1	
	Power of Attorney (may include Associate POA)		2	2	
Warnings:					
Information	:				
Total Files Size (in bytes): 9734					

Millei

This Acknowledgement Receipt evidences receipt on the noted date by the USPTO of the indicated documents, characterized by the applicant, and including page counts, where applicable. It serves as evidence of receipt similar to a Post Card, as described in MPEP 503.

New Applications Under 35 U.S.C. 111

If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

National Stage of an International Application under 35 U.S.C. 371

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.